

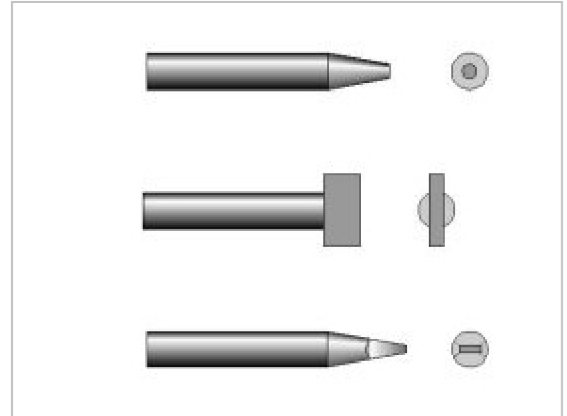
## Bonding Tips

## Instruction: INS1059

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Bonding Tips are used with the Bonding Station and Bonding System. The flat bottom machined surface of each Bonding Tip is used to apply heat and pressure to bond adhesive backed Circuit Frames to a circuit board surface. Bonding Tips are machined from high grade aluminum.

Circuit Frames are available in hundreds of shapes including lands, pads and edge contacts. See [www.circuitmedic.com/products/circuitframes.html](http://www.circuitmedic.com/products/circuitframes.html).



### Pressure

Pressure is the recommended force in pounds to apply to the top surface of the replacement pad, land, or conductor based on the Bonding Tip surface area. The recommended Bonding Pressure for Circuit Frames is 200 - 400 psi.

### Setting

The setting corresponds to the indication on the scale of No. 115-4100 Bonding System. See [www.circuitmedic.com/products/115-4100.html](http://www.circuitmedic.com/products/115-4100.html).

### Available Bonding Tip Sizes

Part No.	Description	Pressure	Setting	Bonding Iron/Station
115-2104	Bonding Tip, Tapered	N/A	N/A	115-3104/115-3105
115-2204	Bonding Tip, .080" (2.03 mm) Diameter	1.00 lbs	4	115-3104/115-3105
115-2206	Bonding Tip, .120" (3.05 mm) Diameter	2.26 lbs	9	115-3104/115-3105
115-2306	Bonding Tip, .040" x .060" (1.02 mm x 1.52 mm)	0.48 lbs	2	115-3104/115-3105
115-2316	Bonding Tip, .080" x .120" (2.03 mm x 3.05 mm)	1.92 lbs	8	115-3104/115-3105
115-2801	Bonding Tip, Tapered	N/A	N/A	115-3210/115-3220
115-2802	Bonding Tip, .080" (2.03 mm) Diameter	1.00 lbs	4	115-3210/115-3220
115-2803	Bonding Tip, .120" (3.05 mm) Diameter	2.26 lbs	9	115-3210/115-3220
115-2804	Bonding Tip, .040" x .060" (1.02 mm x 1.52 mm)	0.48 lbs	2	115-3210/115-3220
115-2805	Bonding Tip, .080" x .120" (2.03 mm x 3.05 mm)	1.92 lbs	8	115-3210/115-3220